



Material Content Data Sheet



Sales Product Name		BSP296N H6327		Issued		27. September 2017			
MA#		MA001098562							
Package		PG-SOT223-4-21		Weight*		113.53 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.006	0.01		51		
	noble metal	gold	7440-57-5	0.023	0.02		199		
	inorganic material	silicon	7440-21-3	0.345	0.30	0.33	3040	3290	
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89		
	non noble metal	titanium	7440-32-6	0.051	0.04		447		
	non noble metal	chromium	7440-47-3	0.152	0.13		1340		
	non noble metal	copper	7440-50-8	50.489	44.47	44.65	444725	446601	
wire	non noble metal	copper	7440-50-8	0.073	0.06	0.06	642	642	
encapsulation	organic material	carbon black	1333-86-4	0.604	0.53		5321		
	plastics	epoxy resin	-	9.061	7.98		79808		
	inorganic material	silicondioxide	60676-86-0	50.739	44.71	53.22	446924	532053	
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12895	12895	
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4519	4519	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com